

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant	:	Uzoh et al.
Appl. No.	:	10/769605
Filed	:	January 30, 2004
For	:	METHOD OF ELECTROPLATING COPPER LAYERS WITH FLAT TOPOGRAPHY
Examiner	:	Smith, Nicholas A.
Group Art Unit	:	1742
Confirmation No.	:	8773

RESPONSE ACCOMPANYING RCE

**Mail Stop Amendment**  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Dear Sir:

Prior to examination of the RCE application filed herewith, please enter the amendments and remarks as set forth herein in the above-captioned application.

**Amendments to the Claims** are reflected in the listing of claims which begins on page 2 of this paper.

**Remarks/Arguments** begin on page 6 of this paper.